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(54) **COMMUNICATION CONNECTOR HAVING A CONTACT MODULE STACK**

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H01R 13/6599	(2011.01)
H01R 13/6587	(2011.01)

(52) **U.S. Cl.**
CPC ***H01R 13/6586*** (2013.01); ***H01R 13/6587*** (2013.01); ***H01R 13/6599*** (2013.01)

(58) **Field of Classification Search**
CPC H01R 13/6585; H01R 13/6586; H01R 13/6587; H01R 13/6599
USPC 439/607.02, 607.05–607.07
See application file for complete search history.

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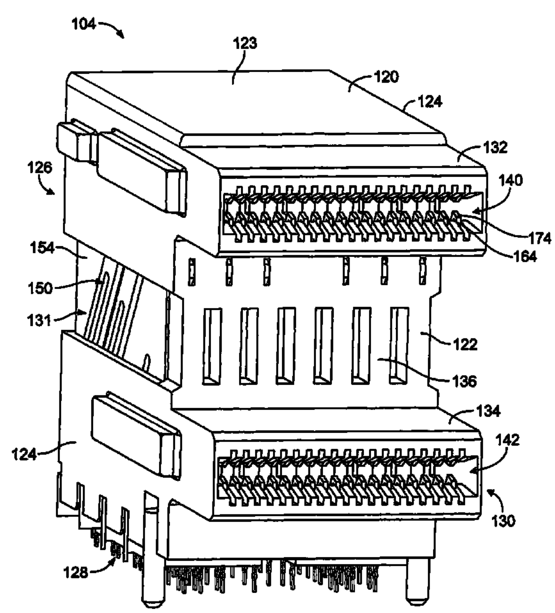
Primary Examiner — Khiem Nguyen

(57) **ABSTRACT**

A contact module stack includes signal contact modules and ground contact modules flanking the signal contact modules in a ground-signal-signal-ground contact module arrangement. The signal contact modules each include signal leadframes and signal dielectric bodies. The ground contact modules each include ground leadframes and ground dielectric bodies. The ground leadframes each have at least one ground contact. Each ground dielectric body has a low loss layer on a first side of the ground leadframe and a lossy layer on a second side of the ground leadframe. The lossy layer and the low loss layer substantially enclose a transition portion of the ground contact. The lossy layers are manufactured from lossy material having conductive particles in a dielectric binder material. The lossy layers absorb electrical resonance propagating through the contact module stack.

20 Claims, 5 Drawing Sheets



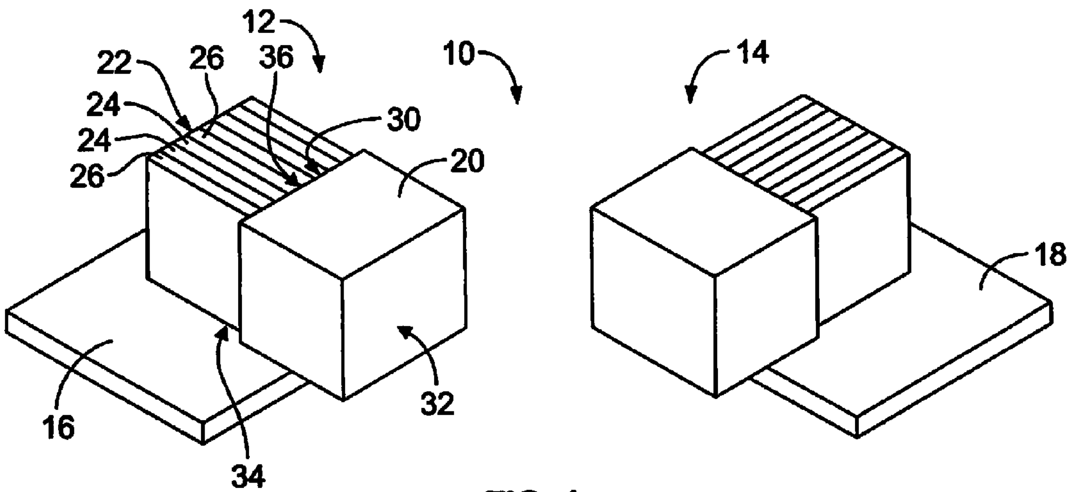

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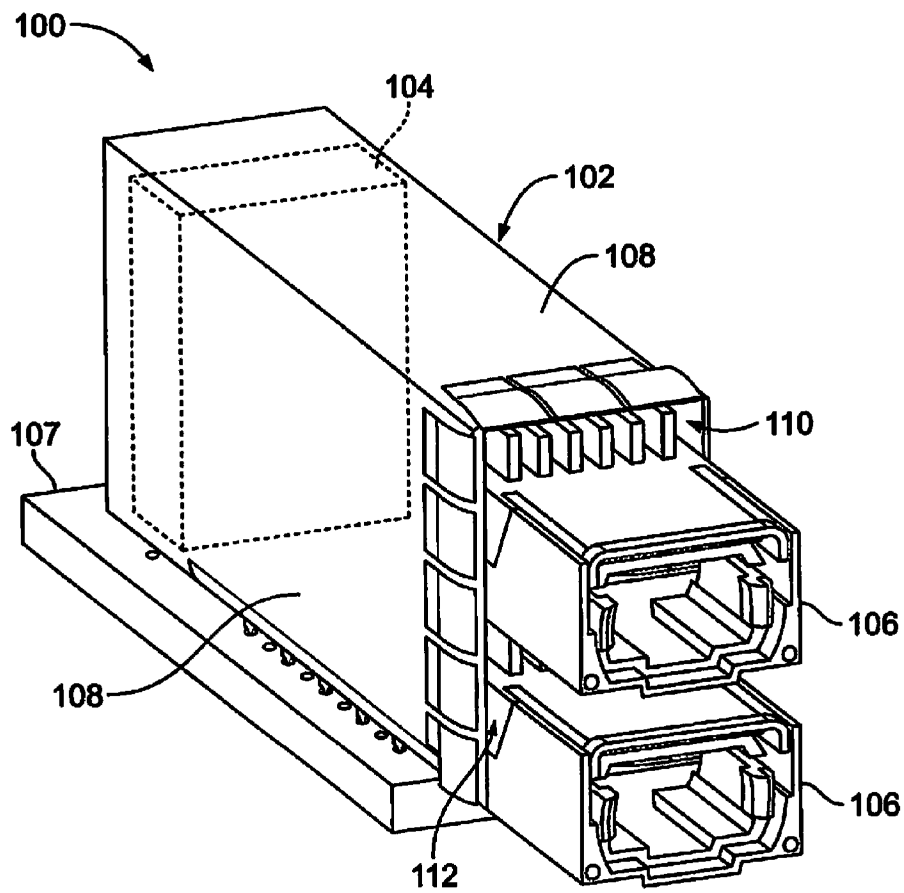
FIG. 1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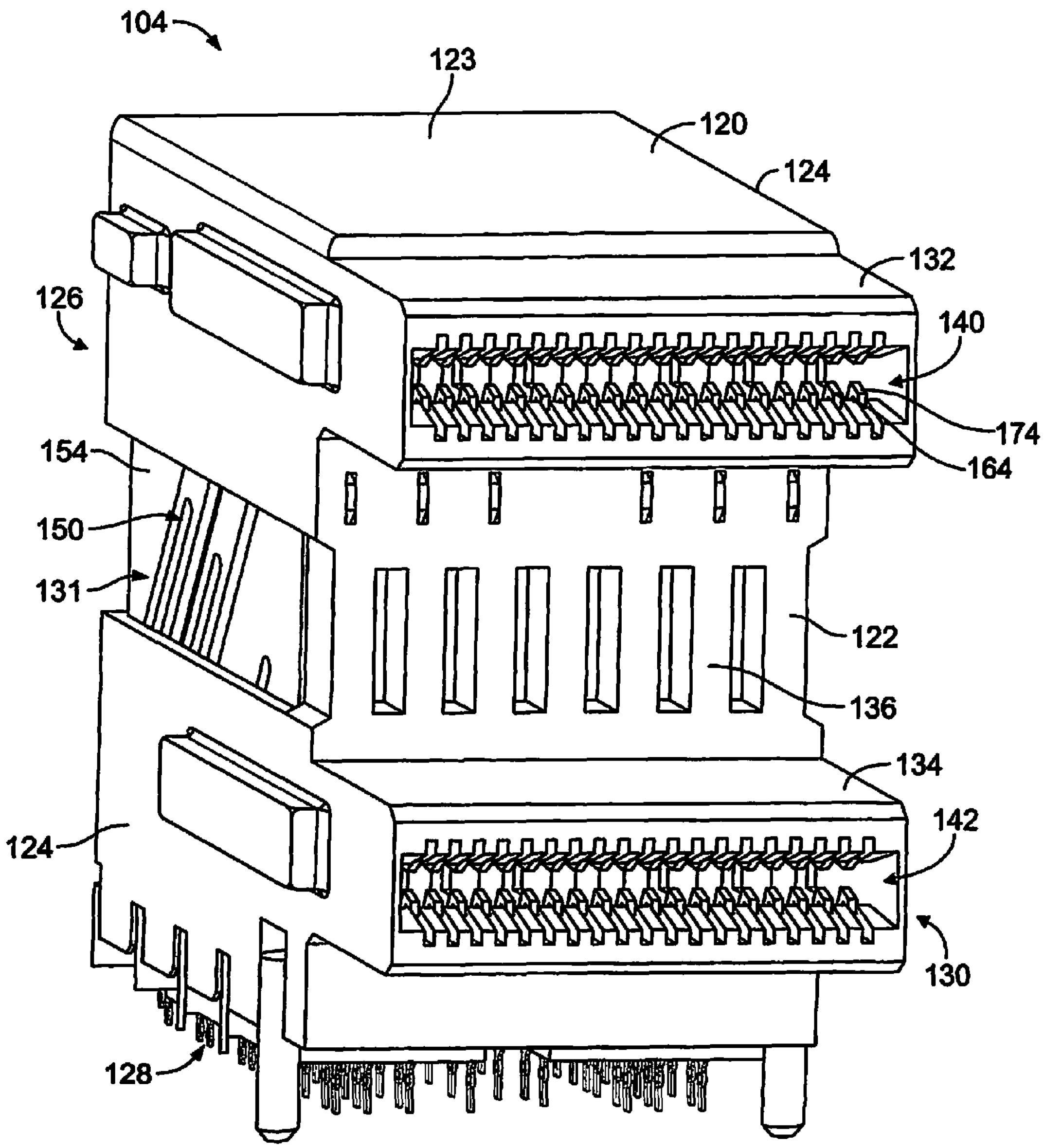
112

FIG. 2


104
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131
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124
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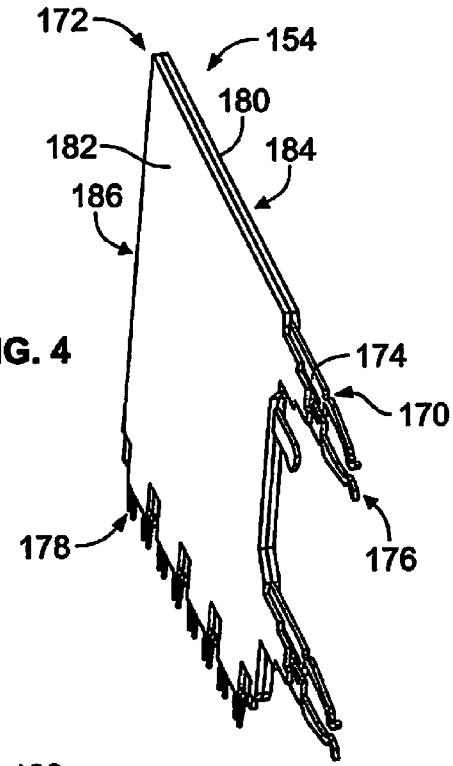
130
128

FIG. 3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154
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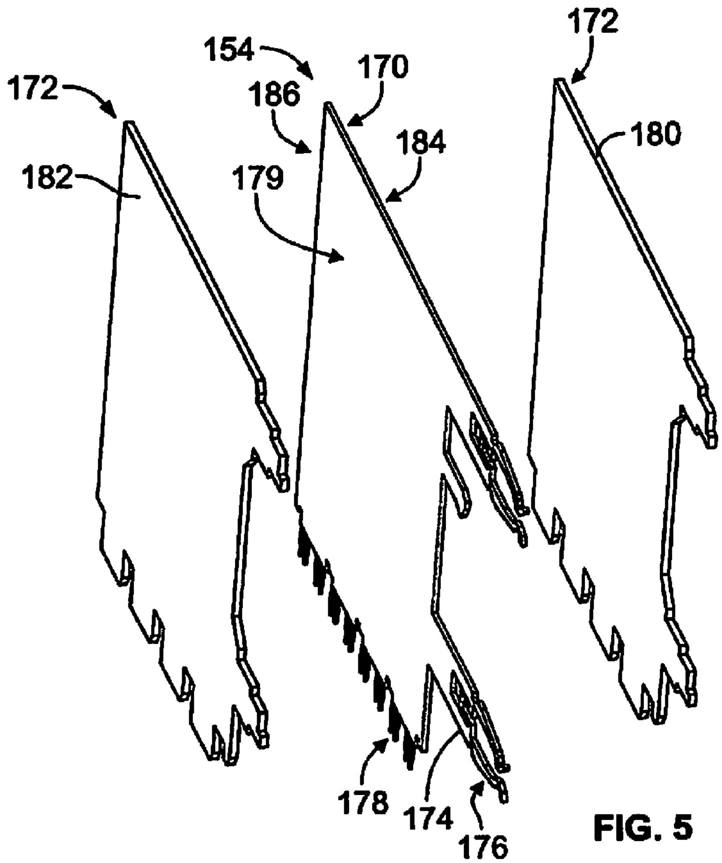
FIG. 4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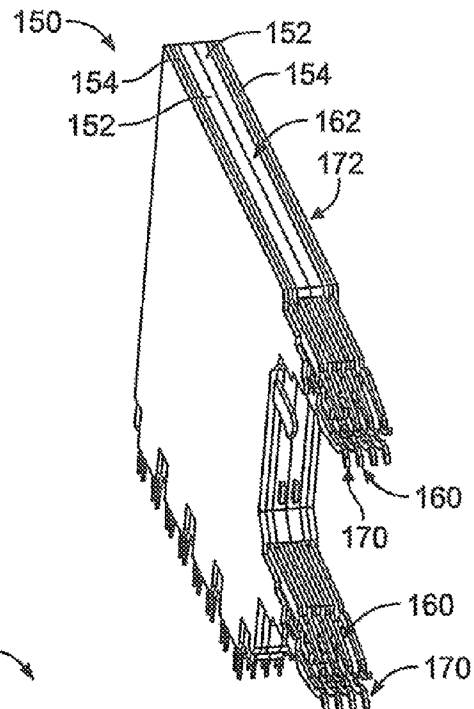
176

FIG. 5


150
152
154
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162
172
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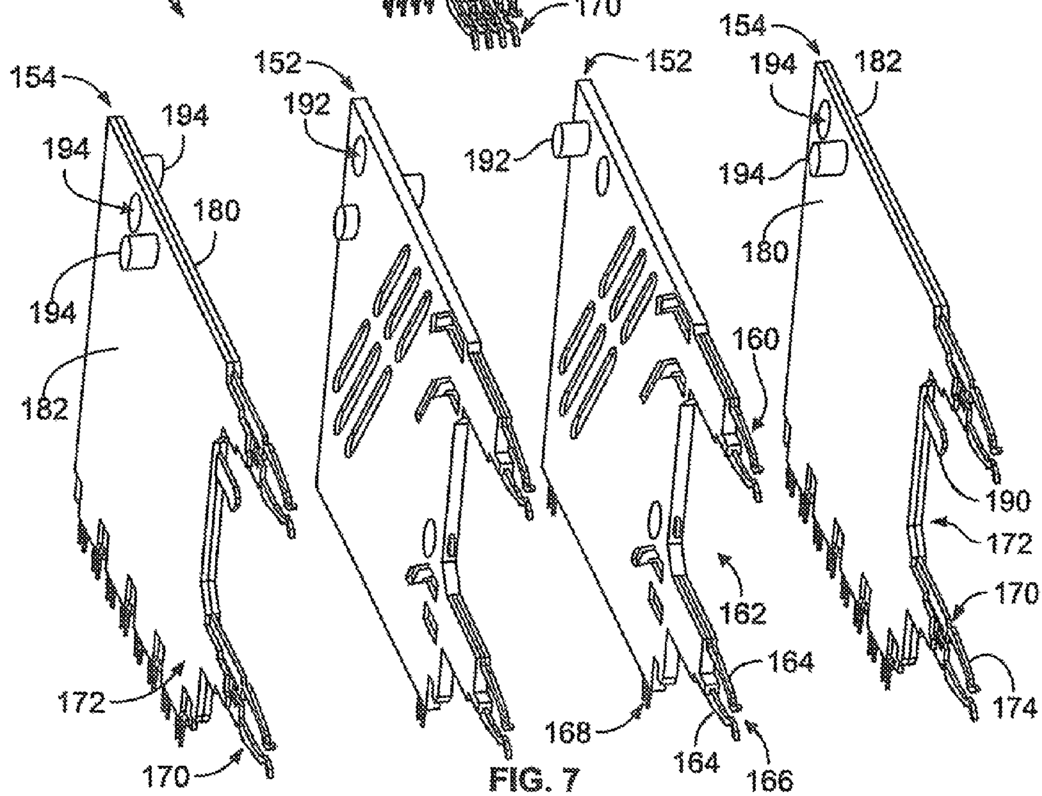
170

FIG. 6


150
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174

FIG. 7

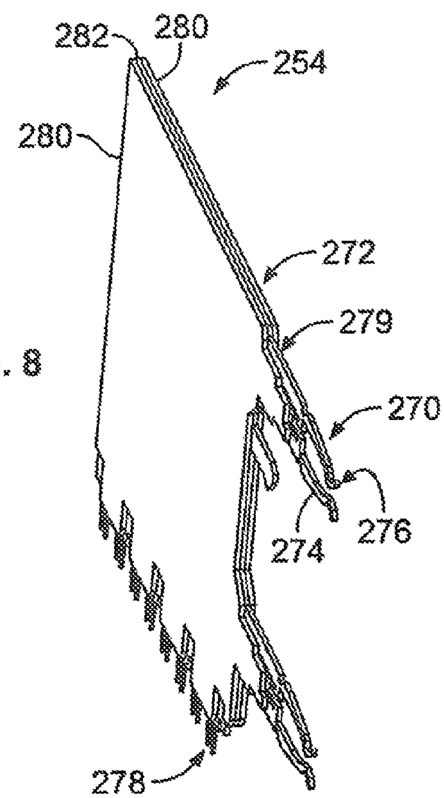
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FIG. 8

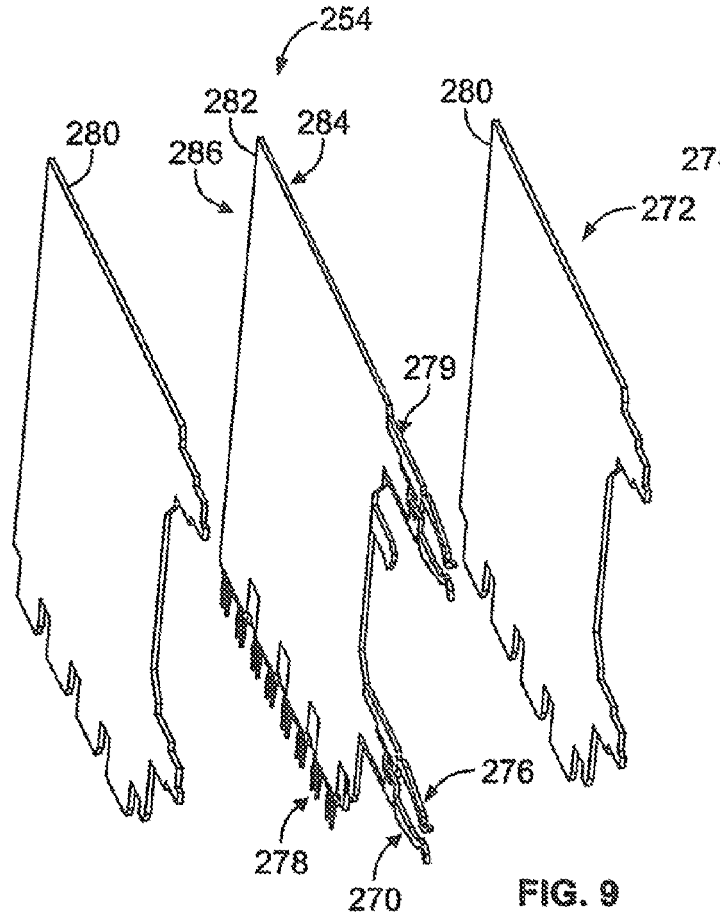
254
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FIG. 9

COMMUNICATION CONNECTOR HAVING A CONTACT MODULE STACK

BACKGROUND OF THE INVENTION

The subject matter herein relates generally to communication connectors.

Some electrical connector systems utilize communication connectors to interconnect various components of the system for data communication. Some known communication connectors have performance problems, particularly when transmitting at high data rates. For example, the communication connectors typically utilize differential pair signal conductors to transfer high speed signals. Ground conductors improve signal integrity. However, electrical performance of known communication connectors, when transmitting the high data rates, is inhibited by noise from cross-talk and return loss. Such issues are more problematic with small pitch high speed data connectors, which are noisy and exhibit higher than desirable return loss due to the close proximity of signal and ground contacts. Energy from ground contacts on either side of the signal pair may be reflected in the space between the ground contacts and such noise results in reduced connector performance and throughput.

A need remains for a high density, high speed electrical connector assembly having reliable performance.

BRIEF DESCRIPTION OF THE INVENTION

In an embodiment, a contact module stack is provided including first and second signal contact modules and first and second ground contact modules flanking the first and second signal contact modules such that the contact module stack has a ground-signal-signal-ground contact module arrangement. The first and second signal contact modules each include corresponding first and second signal leadframes and first and second signal dielectric bodies holding the first and second signal leadframes. The first and second signal leadframes each having plural signal contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends. The first and second signal dielectric bodies substantially enclosing the transition portions. The first and second ground contact modules each include corresponding first and second ground leadframes and first and second ground dielectric bodies holding the first and second ground leadframes. The first and second ground leadframes each have at least one ground contact extending between a corresponding mating end and terminating end with a transition portion between the mating and terminating ends. The first ground dielectric body has a low loss layer on a first side of the first ground leadframe and a lossy layer on a second side of the first ground leadframe. The lossy layer and the low loss layer of the first ground dielectric body substantially encloses the transition portion of the at least one ground contact of the first ground leadframe. The second ground dielectric body has a low loss layer on a first side of the second ground leadframe and a lossy layer on a second side of the second ground leadframe. The lossy layer and the low loss layer of the second ground dielectric body substantially enclose the transition portion of the at least one ground contact of the second ground leadframe. The lossy layers are manufactured from lossy material having conductive particles in a dielectric binder material, the lossy layers absorbing electrical resonance propagating through the contact module stack.

In another embodiment, a communication connector is provided including a housing having a mating end and a loading end. The housing has a cavity open at the loading end. A contact module stack is loaded into the cavity of the housing through the loading end. The contact module stack includes at least one signal contact module each including a signal leadframe and a dielectric body holding the signal leadframes. The signal leadframe has plural signal contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends. The dielectric body substantially encloses the transition portions. The contact module stack includes at least one ground contact module stacked adjacent the corresponding signal contact module. Each ground contact module includes a ground leadframe and a ground dielectric body holding the ground leadframe. The ground leadframe has at least one ground contact extending between a mating end and a terminating end with a transition portion between the mating and terminating ends. The ground dielectric body has a low loss layer on a first side of the first ground leadframe and a lossy layer on a second side of the first ground leadframe. The lossy layer and the low loss layer of the ground dielectric body substantially enclose the transition portion of the at least one ground contact. The lossy layer is manufactured from lossy material having conductive particles in a dielectric binder material. The lossy layer absorbs electrical resonance propagating through the communication connector.

In a further embodiment, a communication connector is provided including a housing having a mating end and a loading end. The housing has a cavity open at the loading end. The housing has an upper extension portion and a lower extension portion defining upper and lower circuit card receiving slots configured to receive corresponding circuit cards. A contact module stack is loaded into the cavity of the housing through the loading end. The contact module stack includes at least one signal contact module each including a signal leadframe and a dielectric body holding the signal leadframe. The signal leadframe has plural signal contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends. The mating ends extend into corresponding upper and lower extension portions and are positioned in the circuit card receiving slots for interfacing with the corresponding circuit cards. The dielectric body substantially encloses the transition portions. The contact module stack includes at least one ground contact module stacked adjacent the corresponding signal contact module. Each ground contact module includes a ground leadframe and a ground dielectric body holding the ground leadframe. The ground leadframe has ground contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends. The mating ends extend into corresponding upper and lower extension portions and are positioned in the circuit card receiving slots for interfacing with the corresponding circuit cards. The ground dielectric body has a low loss layer on a first side of the first ground leadframe and a lossy layer on a second side of the first ground leadframe. The lossy layer and the low loss layer of the ground dielectric body substantially enclose the transition portion of the at least one ground contact. The lossy layer is manufactured from lossy material having conductive particles in a dielectric binder material. The lossy layer absorbs electrical resonance propagating through the communication connector.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. **1** is a schematic view of an electrical connector system formed in accordance with an embodiment.

FIG. **2** is a front perspective view of an electrical connector assembly formed in accordance with an exemplary embodiment.

FIG. **3** is a front perspective view of a communication connector of the electrical connector assembly shown in FIG. **2** and formed in accordance with an exemplary embodiment.

FIG. **4** is a perspective view of a ground contact module for the communication connector and formed in accordance with an exemplary embodiment.

FIG. **5** is an exploded view of the ground contact module shown in FIG. **4**.

FIG. **6** is a perspective view of a portion of a contact module stack showing ground contact modules and signal contact modules.

FIG. **7** is an exploded view of the contact module stack showing the ground contact modules and the signal contact modules.

FIG. **8** is a perspective view of a ground contact module formed in accordance with an exemplary embodiment.

FIG. **9** is an exploded view of the ground contact module shown in FIG. **8**.

DETAILED DESCRIPTION OF THE INVENTION

FIG. **1** is a schematic view of an electrical connector system **10** formed in accordance with an embodiment. The electrical connector system **10** includes a first communication connector **12** and a second communication connector **14** that are configured to be directly mated together. The electrical connector system **10** may be disposed on or in an electrical component, such as a server, a computer, a router, or the like.

In an exemplary embodiment, the first communication connector **12** and the second communication connector **14** are configured to be electrically connected to respective first and second circuit boards **16**, **18**. The first and second communication connectors **12**, **14** are utilized to provide a signal transmission path to electrically connect the circuit boards **16**, **18** to one another at a separable mating interface.

The communication connector **12** includes a housing **20** holding a contact module stack **22** comprising a plurality of signal contact modules **24** and a plurality of ground contact modules **26** in a stacked arrangement. The contact modules **24**, **26** may be wafers. In an exemplary embodiment, the signal and ground contact modules **24**, **26** are arranged in a ground-signal-signal-ground arrangement with pairs of signal contact modules **24** flanked by ground contact modules **26**. The signal contact modules **24** have pairs of contacts (for example, arranged in differential pairs) and the ground contact modules **26** provide shielding for the signal contact modules **24**. Optionally, the signal contact modules **24** are high-speed signal contact modules transmitting high speed data signals. Optionally, at least some of the signal contact modules **24** may be low-speed signal contact modules transmitting lower speed signals, such as control signals. The housing **20** includes multiple walls that define a cavity **30** that receives the contact module stack **22**. The housing **20** extends between a mating end **32** and a mounting end **34**, which is mounted to the circuit board **16**. The cavity **30** is open at a loading end **36** to receive the contact module stack **22**.

In an exemplary embodiment, the contact module stack **22** includes lossy material configured to absorb at least some electrical resonance that propagates along the current paths defined by the signal contacts and/or the ground contacts through the communication connector **12**. For example, the lossy material may be provided in the ground contact modules **26**. The lossy material provides lossy conductivity and/or magnetic lossiness through a portion of the communication connector **12**. The lossy material is able to conduct electrical energy, but with at least some loss. The lossy material is less conductive than conductive material, such as the conductive material of the contacts. The lossy material may be designed to provide electrical loss in a certain, targeted frequency range. The lossy material may include conductive particles (or fillers) dispersed within a dielectric (binder) material. The dielectric material, such as a polymer or epoxy, is used as a binder to hold the conductive particle filler elements in place. These conductive particle filler elements then impart loss that converts the dielectric material to a lossy material. In some embodiments, the lossy material is formed by mixing binder with filler that includes conductive particles. Examples of conductive particles that may be used as a filler to form electrically lossy materials include carbon or graphite formed as fibers, flakes, or other particles. Metal in the form of powder, flakes, fibers, or other conductive particles may also be used to provide suitable lossy properties. Alternatively, combinations of fillers may be used. For example, metal plated (or coated) particles may be used. Silver and nickel may also be used to plate particles. Plated (or coated) particles may be used alone or in combination with other fillers, such as carbon flakes. In some embodiments, the fillers may be present in a sufficient volume percentage to allow conducting paths to be created from particle to particle. For example when metal fiber is used, the fiber may be present at an amount up to 40% by volume or more. The lossy material may be magnetically lossy and/or electrically lossy. For example, the lossy material may be formed of a binder material with magnetic particles dispersed therein to provide magnetic properties. The magnetic particles may be in the form of flakes, fibers, or the like. Materials such as magnesium ferrite, nickel ferrite, lithium ferrite, yttrium garnet and/or aluminum garnet may be used as magnetic particles. In some embodiments, the lossy material may simultaneously be an electrically-lossy material and a magnetically-lossy material. Such lossy materials may be formed, for example, by using magnetically-lossy filler particles that are partially conductive or by using a combination of magnetically-lossy and electrically-lossy filler particles

As used herein, the term "binder" encompasses material that encapsulates the filler or is impregnated with the filler. The binder material may be any material that will set, cure, or can otherwise be used to position the filler material. In some embodiments, the binder may be a thermoplastic material such as those traditionally used in the manufacture of communication connectors. The thermoplastic material may be molded, such as molding of the ground contact modules **26** into the desired shape and/or location. However, many alternative forms of binder materials may be used. Curable materials, such as epoxies, can serve as a binder. Alternatively, materials such as thermosetting resins or adhesives may be used.

Optionally, the communication connector **14** may be similar to the communication connector **12**. For example, the communication connector **14** may include a contact module stack similar to the contact module stack **22** and may include ground contact modules with lossy material. In other various embodiments, the communication connector **14** may be another type of connector. For example, the communication connector **14** may be a high speed transceiver module having a circuit card configured to mate with the communication connector **12**. In such embodiments, the communication connector **14** does not include a contact module stack.

FIG. **2** is a front perspective view of an electrical connector assembly **100** formed in accordance with an exemplary embodiment. The electrical connector assembly **100** includes a cage member **102** and a communication connector **104** (shown schematically in FIG. **2**, also illustrated in FIG. **3**) received in the cage member **102**. Pluggable modules **106** are loaded into the cage member **102** for mating with the communication connector **104**. The cage member **102** and communication connector **104** are intended for placement on and electrical connection to a circuit board **107**, such as a motherboard. The communication connector **104** is arranged within the cage member **102** for mating engagement with the pluggable modules **106**. In an exemplary embodiment, the pluggable module **106** includes a circuit card (not shown) configured to be plugged into the communication connector **104**.

The cage member **102** is a shielding, stamped and formed cage member that includes a plurality of shielding walls **108** that define multiple ports **110**, **112** for receipt of the pluggable modules **106**. In the illustrated embodiment, the cage member **102** constitutes a stacked cage member having the ports **110**, **112** in a stacked configuration. Any number of ports may be provided in alternative embodiments. In the illustrated embodiment, the cage member **102** includes the ports **110**, **112** arranged in a single column, however, the cage member **102** may include multiple columns of ganged ports **110**, **112** in alternative embodiments (for example, 2×2, 3×2, 4×2, 4×3, etc.). The communication connector **104** is configured to mate with the pluggable modules **106** in both stacked ports **110**, **112**. Optionally, multiple communication connectors **104** may be arranged within the cage member **102**, such as when multiple ports are provided.

FIG. **3** is a front perspective view of the communication connector **104** in accordance with an exemplary embodiment. The communication connector **104** includes a housing **120** holding a contact module stack **150**. The housing **120** is defined by an upstanding body portion **122** having a top **123**, sides **124**, a loading end **126**, a mounting end **128** configured to be mounted to the circuit board **107** (shown in FIG. **2**), and a mating end **130**. In the illustrated embodiment, the mating end **130** is located at a front, the loading end **126** is located at the rear opposite the mating end **130**, and the mounting end **128** is located at a bottom of the housing **120**; however, other configurations are possible in alternative embodiments. The body portion **122** may be molded from a dielectric material, such as a plastic material, to rum the housing **120**, The housing **120** has a cavity **131** open at the loading end **126** configured to receive the contact module stack **150**.

Upper and lower extension portions **132** and **134** extend from the body portion **122** to define a stepped mating face. A recessed face **136** is provided between the extension portions **132**, **134**. For a single port cage member, the communication connector **104** may only include a single extension portion. Circuit card receiving slots **140** and **142** extend inwardly from the mating face of each of the respective upper and lower extension portions **132**, **134**, and extend inwardly to the body portion **122**. The circuit card receiving slots **140**, **142** are configured to receive card edges of circuit cards of the corresponding pluggable modules **106** (shown in FIG. **2**). A plurality of contacts **164**, **174** of the contact module stack **150** are exposed within the circuit card receiving slots **140**, **142** for mating with contact pads on the circuit card of the corresponding pluggable module **106**. The contacts **164**, **174** have tails that extend from the mounting end **128** for termination to the circuit board **107**. For example, the tails of the contacts **164**, **174** may constitute pins that are received in plated vias of the motherboard. Alternatively, the tails of the contacts **164**, **174** may be terminated to the circuit board **107** in another manner, such as by surface mounting to the circuit board **107**.

The contact module stack **150** includes signal contact modules **152** (shown in FIGS. **6** and **7**) and ground contact modules **154** providing electrical shielding for the signal contact modules **152**. Optionally, the ground contact modules **154** may flank and be positioned between pairs of signal contact modules **152**, such as in a ground-signal-signal-ground contact module arrangement. Any number of signal and ground contact modules **152**, **154** may be provided in the contact module stack **150** and may be positioned in any order. The signal contact modules **152** each include a signal leadframe **160** (shown in FIG. **7**) and a signal dielectric body **162** (shown in FIG. **7**). The ground contact modules **154** each include a ground leadframe **170** (shown in FIG. **5**) and a ground dielectric body **172** (shown in FIG. **5**).

In an exemplary embodiment, each ground dielectric body **172** includes lossy material configured to absorb at least some electrical resonance that propagates along the signal leadframe **160** and/or the ground leadframe **170**. For example, the lossy material may form part of the ground dielectric body **172**. At least a portion of the ground dielectric body **172** may be molded using lossy material. The lossy material provides lossy conductivity and/or magnetic lossiness through a portion of the ground contact module **154**. The lossy material is able to conduct electrical energy, but with at least some loss. The lossy material is less conductive than conductive material, such as the conductive material of the ground leadframe **170**. The lossy material may be designed to provide electrical loss in a certain, targeted frequency range. The lossy material may include conductive particles (or fillers) dispersed within a dielectric (binder) material. The dielectric material, such as a polymer or epoxy, is used as a binder to hold the conductive particle filler elements in place. These conductive particle filler elements then impart loss that converts the dielectric material to lossy material. In some embodiments, the lossy material is formed by mixing binder with filler that includes conductive particles. Examples of conductive particles that may be used as a filler to form electrically lossy materials include carbon or graphite formed as fibers, flakes, or other particles. Metal in the form of powder, flakes, fibers, or other conductive particles may also be used to provide suitable lossy properties. Alternatively, combinations of fillers may be used. For example, metal plated (or coated) particles may be used. Silver and nickel may also be used to plate particles. Plated (or coated) particles may be used alone or in combination with other fillers, such as carbon flakes. In some embodiments, the fillers may be present in a sufficient volume percentage to allow conducting paths to be created from particle to particle. For example when metal fiber is used, the fiber may be present at an amount up to 40% by volume or more.

FIG. **4** is a perspective view of the ground contact module **154** in accordance with an exemplary embodiment. FIG. **5** is an exploded view of the ground contact module **154**. The ground leadframe **170** includes at least one ground contact **174** extending between a mating end **176** and a terminating end **178** with a transition portion **179** between the mating and terminating ends **176**, **178**. In the illustrated embodiment, the mating end **176** is at the front of the ground contact module **154** and the terminating end **178** is at the bottom of the contact module **154**. The transition portion **179** transitions 90° between the mating and terminating ends **176**, **178**. Other configurations are possible in alternative embodiments. The mating end **176** is configured to mate with the pluggable module **106** (shown in FIG. **2**), such as with the circuit card of the pluggable module **106**. The terminating end **178** is configured to be terminated to the circuit board **107** (shown in FIG. **2**), such as using compliant pins press fit into plated vias of the circuit board **107** or surface tails surface mounted to the circuit board **107**. The terminating ends **178** may be terminated in other ways in alternative embodiments to the circuit board or to another component, such as to ends of wires or cables.

The ground dielectric body **172** encases the ground leadframe **170**, such as the transition portions **179**. In an exemplary embodiment, the mating ends **176** extend forward of the ground dielectric body **172** and the terminating ends **178** extend below the ground dielectric body **172**. The ground dielectric body **172** may be an overmolded dielectric body overmolded over the ground leadframe **170**. Alternatively, the ground dielectric body **172** may be pre-molded pieces coupled together around the ground leadframe **170**.

In an exemplary embodiment, the ground dielectric body **172** includes lossy material. For example, the ground dielectric body **172** includes at least one low loss layer **180** and at least one lossy layer **182**. The lossy layer **182** is manufactured from lossy material, such as lossy material having conductive particles in a dielectric binder material, which absorbs and dissipates electrical resonance propagating through the ground contact module **154**. The lossy material has dielectric properties that vary with frequency. The low loss layer **180** is manufactured from a low loss dielectric material, such as a plastic material. The low loss dielectric material has dielectric properties that have relatively little variation with frequency. The lossy layer(s) **182** and the low loss layer(s) **180** substantially enclose the transition portions **179** of the ground contact **174**. In the illustrated embodiment, the ground dielectric body **172** includes a single low loss layer **180** on a first side **184** and a single lossy layer **182** on a second side **186**; however, other embodiments may include two low loss layers **180** positioned on the first and second sides **184**, **186** and/or two lossy layers **182** positioned on the first and second sides **184**, **186**.

In an exemplary embodiment, the low loss layer **180** directly engages the transition portion **179** of the ground contact **174**, such as at the first side **184**, and the lossy layer **182** directly engages the transition portion **179** of the ground contact **174**, such as at the second side **186**. The low loss layer **180** and/or the lossy layer **182** may directly engage the edges of the transition portion **179** between the sides **184**, **186**. The low loss layer **180** and the lossy layer **182** may form overmolded layers of the ground dielectric body **172**. For example, the low loss layer **180** and the lossy layer **182** may be overmolded over the ground leadframe **170** in a multistage overmolding process. Optionally, the lossy layer **182** may be overmolded over the ground leadframe **170** first and then the low loss layer **180** may be overmolded over the ground leadframe **170** and/or the lossy layer **182**. Alternatively, the low loss layer **180** may be overmolded over the ground leadframe **170** first and then the lossy layer **182** may be overmolded over the ground leadframe **170** at the other side. The overmolding is a multi-shot overmolding, such as a two-stage molding. If other layers are used, the overmolding may be performed in more stages. In other various embodiments, rather than being overmolded together, the lossy layer **182** and the low loss layer **180** may be separately molded, such as with the lossy layer **182** being overmolded over the ground leadframe **170** and the low loss layer **180** being separately molded, and then the lossy layer **182** and the low loss layer **180** may be laminated or otherwise coupled together.

Electrical performance of the communication connector **104** is enhanced by the inclusion of the lossy material in the ground contact modules **154**. For example, at various data rates, including high data rates, return loss is inhibited by the lossy layers **182**. For example, the return loss of the small pitch, high speed data of the contact module stack **150** due to the close proximity of signal and ground contacts **164**, **174** is reduced by the lossy layers **182**. For example, energy from the ground contacts **174** on either side of the signal pair reflected in the space between the ground contacts **174** is absorbed, and thus connector performance and throughput is enhanced.

FIG. **6** is a perspective view of a portion of the contact module stack **150** showing first and second ground contact modules **154** flanking first and second signal contact modules **152**. FIG. **7** is an exploded view of the contact module stack **150** showing the ground contact modules **154** and the signal contact modules **152**. Any number of the signal and ground contact modules **152**, **154** may be stacked together.

The signal leadframe **160** includes at least one signal contact **164** extending between a mating end **166** and terminating end **168** with a transition portion between the mating and terminating ends **166**, **168**. In the illustrated embodiment, the mating end **166** is at the front of the signal contact module **152** and the terminating end **168** is at the bottom of the signal contact module **152**. The transition portion transitions 90° between the mating and terminating ends **166**, **168**. Other configurations are possible in alternative embodiments. The mating end **166** is configured to mate with the pluggable module **106** (shown in FIG. **2**), such as with the circuit card of the pluggable module **106**. The terminating end **168** is configured to be terminated to the circuit board **107** (shown in FIG. **2**), such as using compliant pins press fit into plated vias of the circuit board **107** or surface tails surface mounted to the circuit board **107**. The terminating ends **168** may be terminated in other ways in alternative embodiments to the circuit board or to another component, such as to ends of wires or cables.

The signal dielectric body **162** encases the transition portions of the signal leadframe **160**. The signal dielectric body **162** may be an overmolded dielectric body overmolded over the signal leadframe **160**. Alternatively, the signal dielectric body **162** may be pre-molded pieces coupled together around the signal leadframe **160**.

In the illustrated embodiment, the low loss layers **180** of the ground contact modules **154** face the signal contact modules **152**. Alternatively, the lossy layers **182** of the ground contact modules **154** may face the signal contact modules **152**. In other various embodiments, low loss layers **180** may be provided on both exterior sides of the ground contact modules **154** such that the low loss layers **180** encase the lossy layer **182** and define the exterior sides of the ground contact modules **154**.

The ground leadframes **170** include barbs **190** extending forward from the front edges of the ground dielectric bodies **172**. The barbs **190** may be loaded into corresponding slots in the housing **120** (shown in FIG. **3**) to align and/or secure the ground contact modules **154** in the housing **120**.

The signal and ground contact modules **152**, **154** include retention features **192**, **194**, respectively, that cooperate to secure the signal and ground contact modules **152**, **154** together. For example, the retention features **192** and/or **194** may be posts, openings or other features that align and/or secure the signal dielectric bodies **162** together and align and/or secure the ground dielectric bodies **172** to the signal dielectric bodies **162**.

When the contact module stack **150** is assembled, the ground contact modules **154** provide electrical shielding for the signal contact modules **152**. The conductive ground contacts **174** provide electrical shielding to shield the pairs of signal contacts **164** from other pairs of signal contacts **164**, such as signal contacts in another part of the contact module stack **150** (for example, on the opposite side of one or both of the ground contact modules **154**). The electrical shielding improves electrical performance of the communication connector **104** (shown in FIG. **3**). The lossy material of the lossy layers **182** further improves electrical performance of the communication connector **104** by absorbing electrical resonance propagating through the contact module stack **150**. The lossy material lowers the energy reflected along the signal and/or ground contacts **174**, **164**, thus improving performance.

FIG. **8** is a perspective view of a ground contact module **254** formed in accordance with an exemplary embodiment. FIG. **9** is an exploded view of the ground contact module **254**. The ground contact module **254** may be used in place of the ground contact module **154** (shown in FIG. **6**). The ground contact module **254** includes a ground leadframe **270** and ground dielectric bodies **272**. The ground leadframe **270** includes at least one ground contact **274** extending between a mating end **276** and terminating end **278** with a transition portion **279** between the mating and terminating ends **276**, **278**. In an exemplary embodiment, each ground dielectric body **272** includes lossy material configured to absorb at least some electrical resonance that propagates along the ground leadframe **270**.

The ground dielectric body **272** encases the ground leadframe **270**, such as the transition portions **279**. The ground dielectric body **272** may be an overmolded dielectric body overmolded over the ground leadframe **270**. Alternatively, the ground dielectric body **272** may be pre-molded pieces coupled together around the ground leadframe **270**.

In an exemplary embodiment, the ground dielectric body **272** includes lossy material. For example, the ground dielectric body **272** includes a pair of low loss layers **280** provided on both sides of a lossy layer **282**; however multiple lossy layers **282** may be provided, such as on opposite sides of the ground leadframe **270**. In the illustrated embodiment, the lossy layer **282** encases the transition portions **279** of the ground leadframe **270** and is provided on both sides thereof. The low loss layers **280** are outside of the lossy layer **282** on both sides thereof. The lossy layer **282** is manufactured from lossy material, such as lossy material having conductive particles in a dielectric binder material, which absorbs and dissipates electrical resonance propagating along the ground contact module **254**. The low loss layers **280** are manufactured from a low loss dielectric material, such as a plastic material. The lossy layer **282** and the low loss layers **280** substantially enclose the transition portions **279** of the ground contact **274**.

The lossy layer **282** is overmolded over the ground leadframe **270** and directly engages the transition portions **279** of the ground contacts **274**, such as at first and second sides **284**, **286**. The low loss layers **280** may then be overmolded over the lossy layer **282**. The overmolding is a multi-shot overmolding. In other various embodiments, rather than being overmolded together, the lossy layer **282** and the low loss layers **280** may be separately molded, such as with the lossy layer **282** being overmolded over the ground leadframe **270** and then the low loss layers **280** being laminated or otherwise coupled to the lossy layer **282**.

It is to be understood that the above description is intended to be illustrative, and not restrictive. For example, the above-described embodiments (and/or aspects thereof) may be used in combination with each other. In addition, many modifications may be made to adapt a particular situation or material to the teachings of the invention without departing from its scope. Dimensions, types of materials, orientations of the various components, and the number and positions of the various components described herein are intended to define parameters of certain embodiments, and are by no means limiting and are merely exemplary embodiments. Many other embodiments and modifications within the spirit and scope of the claims will be apparent to those of skill in the art upon reviewing the above description. The scope of the invention should, therefore, be determined with reference to the appended claims, along with the full scope of equivalents to which such claims are entitled. In the appended claims, the terms "including" and "in which" are used as the plain-English equivalents of the respective terms "comprising" and "wherein." Moreover, in the following claims, the terms "first," "second," and "third," etc. are used merely as labels, and are not intended to impose numerical requirements on their objects. Further, the limitations of the following claims are not written in means-plus-function format and are not intended to be interpreted based on 35 U.S.C. §112(f), unless and until such claim limitations expressly use the phrase "means for" followed by a statement of function void of further structure.

What is claimed is:

1. A contact module stack comprising:

first and second signal contact modules each including a corresponding first and second signal leadframe and a corresponding first and second signal dielectric body holding the corresponding first and second signal leadframe, the first and second signal leadframes each having plural signal contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends, the first and second signal dielectric bodies substantially enclosing the transition portions; and

first and second ground contact modules flanking the first and second signal contact modules such that the contact module stack has a ground-signal-signal-ground contact module arrangement, the first and second ground contact modules each including a corresponding first and second ground leadframe and a corresponding first and second ground dielectric body holding the corresponding first and second ground leadframe, the first and second ground leadframes each having at least one ground contact extending between a corresponding mating end and terminating end with a transition portion between the mating and terminating ends, the first ground dielectric body having a low loss layer on a first side of the first ground leadframe and a lossy layer on a second side of the first ground leadframe, the lossy layer and the low loss layer of the first ground dielectric body substantially enclosing the transition portion of the at least one ground contact of the first ground leadframe, the second ground dielectric body having a low loss layer on a first side of the second ground leadframe and a lossy layer on a second side of the second ground leadframe, the lossy layer and the low loss layer of the second ground dielectric body substantially enclosing the transition portion of the at least one ground contact of the second ground leadframe;

wherein the lossy layers are manufactured from lossy material having conductive particles in a dielectric binder material, the lossy layers absorbing electrical resonance propagating through the contact module stack.

2. The contact module stack of claim **1**, wherein the lossy layer of the first ground dielectric body directly engages the transition portion of the corresponding ground contact of the first ground leadframe.

3. The contact module stack of claim **1**, wherein the lossy layer of the first ground dielectric body is provided on the first side of the first ground leadframe between the first ground leadframe and the low loss layer.

4. The contact module stack of claim **1**, wherein the first ground dielectric body includes a second low loss layer on the second side of the first ground leadframe, the lossy layer being positioned between the first ground leadframe and the second low loss layer.

5. The contact module stack of claim **1**, wherein the lossy layer and the low loss layer of the first ground dielectric body form overmolded layers of the first ground dielectric body overmolded in a multistage overmolded.

6. The contact module stack of claim **1**, wherein the lossy layer and the low loss layer of the first ground dielectric body are laminated together to in case the first ground leadframe.

7. The contact module stack of claim **1**, wherein the lossy material of the lossy layer of the first ground dielectric body directly engages the second side of the transition portion of the ground contact of the first ground leadframe and the edges of the transition portion of the ground contact of the first ground leadframe.

8. The contact module stack of claim **7**, wherein the lossy material of the lossy layer of the first ground dielectric body directly engages the first side of the transition portion of the ground contact of the first ground leadframe.

9. The contact module stack of claim **1**, wherein the low loss layers define outer layers of the first and second ground dielectric bodies, the low loss layers facing the first and second signal dielectric bodies.

10. The contact module stack of claim **1**, wherein the first and second ground dielectric bodies include retention features and the first and second signal dielectric bodies include retention features cooperating with the retention features of the first and second ground dielectric bodies to secure the first and second ground contact modules and the first and second signal contact modules together in the contact module stack.

11. The contact module stack of claim **1**, wherein the low loss layer of the first ground dielectric body is molded around the first ground leadframe and then the lossy layer of the first ground dielectric body is molded onto the low loss layer of the first ground dielectric body and around the first ground leadframe.

12. The contact module stack of claim **1**, wherein the lossy layer of the first ground dielectric body is molded around the first ground leadframe and then the low loss layer of the first ground dielectric body is molded onto the lossy layer of the first ground dielectric body.

13. A communication connector comprising:

a housing having a mating end and a loading end, the housing having a cavity open at the loading end; and

a contact module stack loaded into the cavity of the housing through the loading end, the contact module stack comprising:

at least one signal contact module including a signal leadframe and a dielectric body holding the signal leadframe, the signal leadframe having plural signal contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends, the dielectric body substantially enclosing the transition portions; and

at least one ground contact module stacked adjacent the at least one signal contact module, the at least one ground contact module including a ground leadframe and a ground dielectric body holding the ground leadframe, the ground leadframe having at least one ground contact extending between a mating end and a terminating end with a transition portion between the mating and terminating ends, the ground dielectric body having a low loss layer on a first side of the ground leadframe and a lossy layer on a second side of the ground leadframe, the lossy layer and the low loss layer of the ground dielectric body substantially enclosing the transition portion of the at least one ground contact, wherein the lossy layer is manufactured from lossy material having conductive particles in a dielectric binder material, the lossy layer absorbing electrical resonance propagating through the communication connector.

14. The communication connector of claim **13**, wherein the lossy layer directly engages the transition portion of the at least one ground contact.

15. The communication connector of claim **13**, wherein the lossy layer is provided on the first side of the ground leadframe between the ground leadframe and the low loss layer.

16. The communication connector of claim **13**, wherein the low loss layer is a first low loss layer and the ground dielectric body includes a second low loss layer on the second side of the ground leadframe, the lossy layer being positioned between the ground leadframe and the second low loss layer.

17. The communication connector of claim **13**, wherein the lossy layer and the low loss layer of the ground dielectric body form overmolded layers of the ground dielectric body overmolded in a multistage overmold.

18. A communication connector comprising:

a housing having a mating end and a loading end, the housing having a cavity open at the loading end, the housing having an upper extension portion and a lower extension portion defining upper and lower circuit card receiving slots configured to receive corresponding circuit cards; and

a contact module stack loaded into the cavity of the housing through the loading end, the contact module stack comprising:

at least one signal contact module including a signal leadframe and a dielectric body holding the signal leadframe, the signal leadframe having plural signal contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends, the mating ends extending into corresponding upper and lower extension portions and being positioned in the circuit card receiving slots for interfacing with the corresponding circuit cards, the dielectric body substantially enclosing the transition portions; and

at least one ground contact module stacked adjacent the at least one signal contact module, the at least one ground contact module including a ground leadframe and a ground dielectric body holding the ground leadframe, the ground leadframe having ground contacts extending between mating ends and terminating ends with transition portions between the mating and terminating ends, the mating ends extending into corresponding upper and lower extension portions and being positioned in the circuit card receiving slots for interfacing with the corresponding circuit cards, the ground dielectric body having a low loss layer on a first side of the first ground leadframe and a lossy layer on a second side of the first ground leadframe, the lossy layer and the low loss layer of the ground dielectric body substantially enclosing the transition portion of the at least one ground contact, wherein the lossy layer is manufactured from lossy material having conductive particles in a dielectric binder material, the lossy layer absorbing electrical resonance propagating through the communication connector.

19. The communication connector of claim **18**, wherein the lossy layer directly engages the transition portion of the corresponding ground contact.

20. The communication connector of claim **18**, wherein the lossy layer and the low loss layer of the ground dielectric body form overmolded layers of the ground dielectric body overmolded in a multistage overmold.

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